

Serial No. 09/450,632
Docket No. 550718-070
Second Preliminary Amendment

c 6. A lead-free solder alloy according to claim 3 wherein Ni is added to a ~~solved~~
base alloy of Sn-Cu.

c 7. A lead-free solder alloy according to claim 1 wherein Cu is added to a ~~solved~~
base alloy of Sn-Ni.

c 8. A lead-free solder alloy according to claim 2 wherein Cu is added to a ~~solved~~
base alloy of Sn-Ni.

c 9. A lead-free solder alloy according to claim 3 wherein Cu is added to a ~~solved~~
base alloy of Sn-Ni.

13. A lead-free solder alloy according to claim 1 wherein 0.001-1 wt% Ge is further
added.


4b 14. A lead-free solder alloy according to claim 2 wherein 0.001-1 wt% Ge is further
added.

31 15. A lead-free solder alloy according to claim 3 wherein 0.001-1 wt% Ge is further
added.--

Remarks

The above amendments have been made in order to remove multiple dependent claims.

Respectfully submitted,



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